

| L Number | Hits   | Search Text   | DB  | Time stamp       |
|----------|--------|---|---|------------------|
| -        | 151534 | 438.clas.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/05/25 10:52 |
| -        | 464469 | ((bond\$4 or attach\$4 or connect\$4) with (substrate or wafer or die))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/05/25 10:53 |
| -        | 35962  | 438.clas. and (((bond\$4 or attach\$4 or connect\$4) with (substrate or wafer or die)))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/05/25 10:53 |
| -        | 32015  | ( 438.clas. and (((bond\$4 or attach\$4 or connect\$4) with (substrate or wafer or die)))) and (connect\$5 or interconnect\$5 or electrical)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/05/25 11:29 |
| -        | 29     | (( 438.clas. and (((bond\$4 or attach\$4 or connect\$4) with (substrate or wafer or die)))) and (connect\$5 or interconnect\$5 or electrical)) and (first adj contact adj (element or structure))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/05/25 11:30 |
| -        | 19     | (( 438.clas. and (((bond\$4 or attach\$4 or connect\$4) with (substrate or wafer or die)))) and (connect\$5 or interconnect\$5 or electrical)) and (first adj contact adj (element or structure)) and (second adj contact adj (element or structure)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/05/25 11:31 |